WHAT IS CLAIMED IS:

1. A package structure of a solid-state having a solid-state image sensor chip and a color filter stuck on a light receiving surface of the chip, the package structure comprising:

a vessel for packaging the solid-state image sensor chip;

an optically transparent protection plate attached to the vessel to cover the light receiving surface of the chip; and

a resin layer arranged between the chip and the protection plate to absorb light having a predetermined wavelength.

2. The package structure according to claim 1, wherein the resin layer absorbs light having a wavelength shorter than the wavelength of visible light.

3. The package structure according to claim 1, wherein the vessel includes a cavity having a predetermined length and width to receive the chip, the protection plate having a length that is greater than the length of the cavity and a width that is less than the width of the cavity.

4. A solid-state image sensor comprising:

a solid state image sensor chip including a light receiving surface and a color filter stuck on the light receiving surface;

a vessel including a cavity for receiving the chip;

a resin layer arranged in the cavity to cover the color filter, wherein the resin layer absorbs light having a

predetermined wavelength; and

a protection plate attached to the vessel to cover at least part of the resin layer.

5.   The solid-state image sensor according to claim 4, wherein the resin layer absorbs light having a wavelength shorter than the wavelength of visible light.

6.   The solid-state image sensor according to claim 4, wherein the cavity has a predetermined length and width, the protection plate having a length that is greater than the length of the cavity and a width that is less than the width of the cavity.

7.   The solid-state image sensor according to claim 4, wherein the protection plate is fixed to the vessel so as to form a gap between the protection plate and the cavity, the resin layer being partially exposed by the gap.